semiconductor wafer to have a specific relationship, a dicing die attach film that is less likely to cause any pickup failure can be obtained. The present invention is based on these findings, and after further investigation, has been completed.

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The above problems of the present invention have been solved by the following means.

[1]

A dicing die attach film, including:

a dicing film; and

a die attach film laminated on the dicing film,

wherein the die attach film has an arithmetic average roughness Ra1 of from 0.05 to 2.50 μm at a surface in contact with the dicing film, and

wherein a value of ratio of Ra1 to an arithmetic average roughness Ra2 at a surface that is of the die attach film and is opposite to the surface in contact with the dicing film is from 1.05 to 28.00.

[2]

The dicing die attach film described in [1],

wherein the die attach film includes:

an epoxy resin (A),

an epoxy resin curing agent (B),

a polymer component (C), and

an inorganic filler (D), and

wherein the die attach film is thermally cured to give a cured body having a thermal conductivity of 1.0 W/m·K or more.

[3]

The dicing die attach film described in [1] or [2], wherein when the die attach film is heated at a temperature elevation rate of 5°C/min from 25°C, a melt viscosity at 120°C is in a range of 500 to 10,000 Pa·s.